

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT3990839

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DOMINIK EISERT	12/04/2013
TORSTEN BAADE	11/02/2013
MICHAEL ZITZLSPERGER	11/02/2013
RECEIVING PARTY DATA	
Name:	OSRAM OPTO SEMICONDUCTORS GMBH
Street Address:	LEIBNIZSTR. 4
City:	REGENSBURG
State/Country:	GERMANY
Postal Code:	93055
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15227287
CORRESPONDENCE DATA	
Fax Number:	(215)656-2498
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	EHF-13-1584CON 369254-423
NAME OF SUBMITTER:	T. DANIEL CHRISTENBURY
SIGNATURE:	/TDC/
DATE SIGNED:	08/03/2016
Total Attachments: 6	
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source=Assignment#page5.tif
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ASSIGNMENT

For good and valuable consideration, I (We),

Dominik Eisert,
residing at Agricolaweg 11
93049 Regensburg
Germany
citizen of Germany

Torsten Baade,
residing at Lieblstr. 55
93059 Regensburg
Germany
citizen of Germany

Michael Zitzlsperger,
residing at Schattenhofergasse 4
93047 Regensburg
Germany
citizen of Germany

hereafter individually or collectively referred to as "Assignor(s)";

Hereby, (I) acknowledge having previously assigned, sold and transferred to **OSRAM Opto Semiconductors GmbH**, a corporation organized and existing under the laws of GERMANY, having its principal place of business at Leibnizstr. 4 in 93055 Regensburg, hereinafter "Assignee", its successors, assigns and legal representatives, or to a predecessor of Assignee, pursuant to (A)(i) the laws of GERMANY or (ii) a Patent & Secrecy Agreement or similar legal document such as, without limitation, an employee agreement executed at the time of entering into the employment of, or executed as a condition of continuing employment with, the Assignee or a predecessor of the Assignee, the entire right, including any and all priority rights, title and interest, in and for the United States and all foreign countries, in and to any and all inventions or improvements which are disclosed in an invention disclosure and/or in the below-identified documents currently filed with this Assignment, already filed or granted for Letters Patent (in which case, any provision of the subject Assignment that is in conflict with or is in addition to any provision in the prior agreement(s) or assignment(s) then this Assignment shall govern, take precedence, and be of legal effect), or

(B)(i) to the extent such laws of GERMANY or such Patent & Secrecy Agreement or similar legal document failed or fails, in whole or part, to have assigned, sold or transferred the entire right (including priority rights), title and interest, in and for the United States and all foreign countries, in and to all inventions or improvements which are disclosed in the below-identified application(s) or pending application(s) or granted Letters Patent, or (ii) if no such agreement(s) exist assigning, selling or transferring any such right (including priority rights), title or interest; then for good and valuable consideration, Assignor(s) now and hereby, effective Nunc Pro Tunc on the filing date of the below identified patent application(s), pending patent application(s) or granted Letter Patent(s), assign, sell and transfer(s) to Assignee, its successors, assigns and legal representatives, the entire right, (including all priority rights), title and interest in and for the

United States and all foreign countries, in and to any and all inventions and/or improvements which are disclosed in the following identified; patent application(s), pending patent application(s) or granted Letter Patent(s)

Patent Application Title: OPTOELECTRONIC SEMICONDUCTOR CHIP,
OPTOELECTRONIC SEMICONDUCTOR COMPONENT, AND A METHOD FOR
PRODUCING AN OPTOELECTRONIC SEMICONDUCTOR COMPONENT

Filing Date: (11/18/2013)

Filing Number: 14/118,475

Internal Case Number(s): EHF-13-1584

and in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and


(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



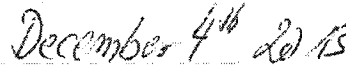
Witness Signature



Dominik Eisert



printed name of witness



Date

Witness Signature

Torsten Baade

printed name of witness

Date

Witness Signature

Michael Zitzlsperger

printed name of witness

Date

Companies Representative(s)
OSRAM Opto Semiconductors GmbH

Signature

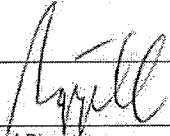


Name

Aldo Kamper
President & CEO

Date

Signature



Name

Josef Ringsgwandl
CFO

Date

04 DEC 2013

ASSIGNMENT

For good and valuable consideration, I (We),

Dominik Eisert,
residing at Agricolaweg 11
93049 Regensburg
Germany
citizen of Germany

Torsten Baade,
residing at Lieblstr. 55
93059 Regensburg
Germany
citizen of Germany

Michael Zitzlsperger,
residing at Schattenhofergasse 4
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(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and/or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and

(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Witness Signature

Dominik Eisert

printed name of witness

Date

K. Bechtloff-Kahn
Witness Signature

K. Bechtloff-Kahn
printed name of witness

Torsten / Baade
Torsten Baade

November 2nd, 2013
Date

Christian Zieris
Witness Signature

CHRISTIAN ZIERIS
printed name of witness

Michael Zitzlperger
Michael Zitzlperger

November 6th, 2013
Date

Companies Representative(s)
OSRAM Opto Semiconductors GmbH

Signature
Name

Date

Signature
Name

Date